Product Information Sheet

EPO-TEK® EK1000-1-D

Date:	February 2023
Rev:	XIV
No. of Components:	Single
Mix Ratio by Weight:	N/A
Specific Gravity:	3.51
Pot Life:	2 Weeks **Dry Time:** < 7 Days
Shelf Life- Bulk:	One year at -40°C
Shelf Life- Syringe:	One year at -40°C

Recommended Cure: 150°C / 1 Hour plus 200°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
200°C / 30 Minutes
150°C / 1 Hour
125°C / 2 Hours

NOTES:
- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A longer dry time and low viscosity version of EPO-TEK® EK1000 designed for applications requiring longer working time and better flowing than provided by EPO-TEK® EK1000.

Typical Properties: Cure condition:150°C / 1 Hour plus 200°C / 1 Hour Different batches, conditions & applications yield differing results. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis Data below is not guaranteed.

PHYSICAL PROPERTIES:			
* Color (before cure):	Silver		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 100 rpm:	1,800 - 3,300	cPs	
Thixotropic Index:	4.8		
* Glass Transition Temp:	≥ 70	°C	(Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):			
Below Tg:	41	x 10^{-6} in/in°C	
Above Tg:	162	x 10^{-6} in/in°C	
Shore D Hardness:	65		
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	372	°C	
Weight Loss:			
@ 200°C:	0.03	%	
@ 250°C:	0.40	%	
@ 300°C:	1.00	%	
Suggested Operating Temperature:	< 300	°C (Intermittent)	
Storage Modulus:	609,195	psi	
Ion Content:	Cl^-: 6 ppm	Na^+:	3 ppm
	NH_4^+: 8 ppm	K^+:	2 ppm
* Particle Size:	≤ 45	microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity (150°C / 1 Hour plus 200°C / 1 Hour):	22.7	W/mK
Thermal Conductivity (150°C / 1 Hour):	12.1	W/mK
* Volume Resistivity @ 23°C (150°C / 1 Hour plus 200°C / 1 Hour):	≤ 0.00008	Ohm-cm

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
www.epotek.com

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